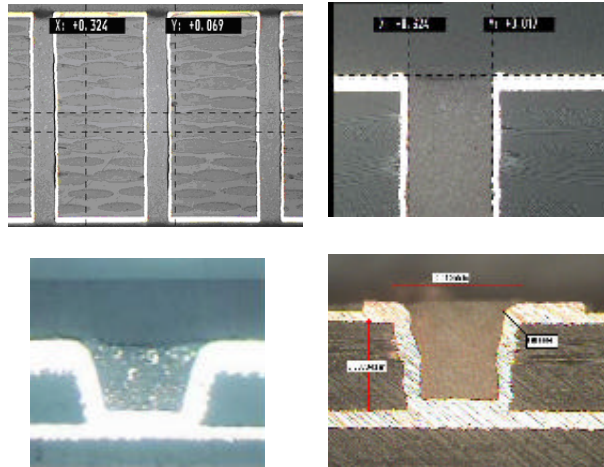


Horizontal Via Hole Filling VHF 300 V with Vacuum



This equipment is designed for pcb via hole filling, through holes and blind vias.

max. Aspect Ratio 1:40



Surfaces planarized with MASS Planarizer SV 100

Function:

The pcb is placed horizontally onto the filling surface and clamped by the clamping system. The door is closed and the vacuum process starts.

The vacuum has built up after about 20 seconds. The plunger (air pressure controlled) is pressing the paste into the holes of the panel. The paste is stored in reusable cartridges. We supply different head's for different panel sizes. The movements of the X- and Y-axis are controlled by servo motors. The touch panel display allows up to 50 recipes to be stored. All process parameters are part of the recipe. Max. 5 tracks and 4 steps are possible for each recipe.

Paste Delivery:

As with the VCP vertical filling machines, the paste delivery is from a standard 12oz or 6oz or smaller cartridge. The paste is pressed into the via fill head via pneumatic pressure on the back of the plunger in the cartridge. Different head sizes can be used. If, however, a head size larger than 6" is required, then the pressure bar assembly must be exchanged against one that allows the capability of pressing a long head up to 24" long evenly across the entire width of the fill area.

Also, as with the vertical VCP machines, face plates with different opening sizes can be used with a given head size.

The pastes for this process are:

- Silver- and copper paste (conductive)
- Epoxy Fill (non conductive) Sanei, Taiyo, Peters, Coates etc.

System Data:

Dimensions	: 60 x 58 x 56", 1525 x 1470 x 1420 mm
Panel size	: max. 24 x 30", max. 610 x 762 mm
Panel thickness	: 2 to 200 mil, 0,05 to 5 mm
Fill system	: 5 - 12" heated fill head
Touch panel	: Siemens S7-300
Paste capacity	: 6 or 12 oz cartridge
Connection	: 480/400V, 3P/N/PE, 50/60 Hz, 4 kW

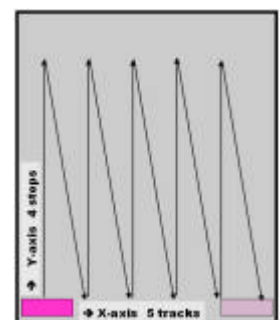
Advantages:

- Via Hole Filling of through holes and blind vias
- Less waste from the very valuable silver paste
- Using high paste pressure to fill high aspect ratio (1:40) boards
- No direct contact between the compressed air and the paste
- Heatable heads are available

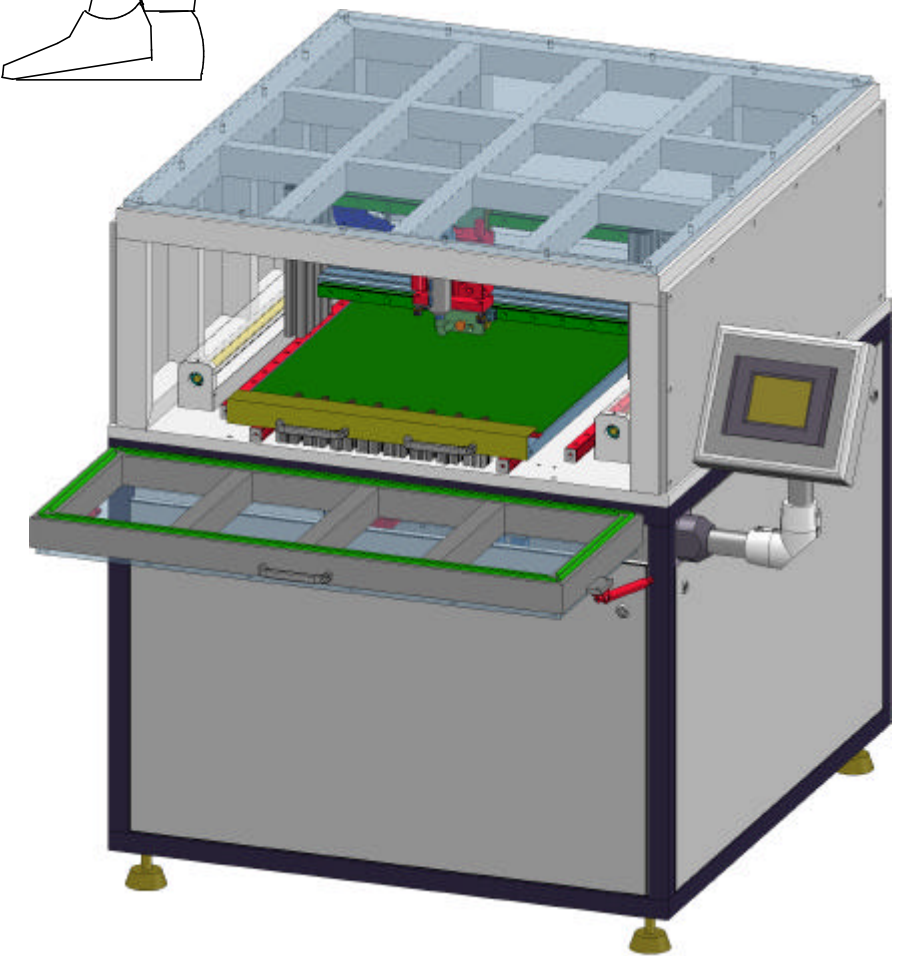
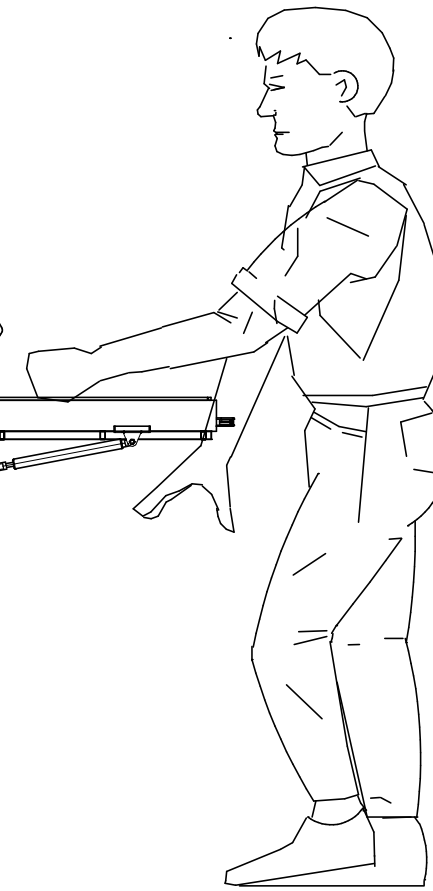
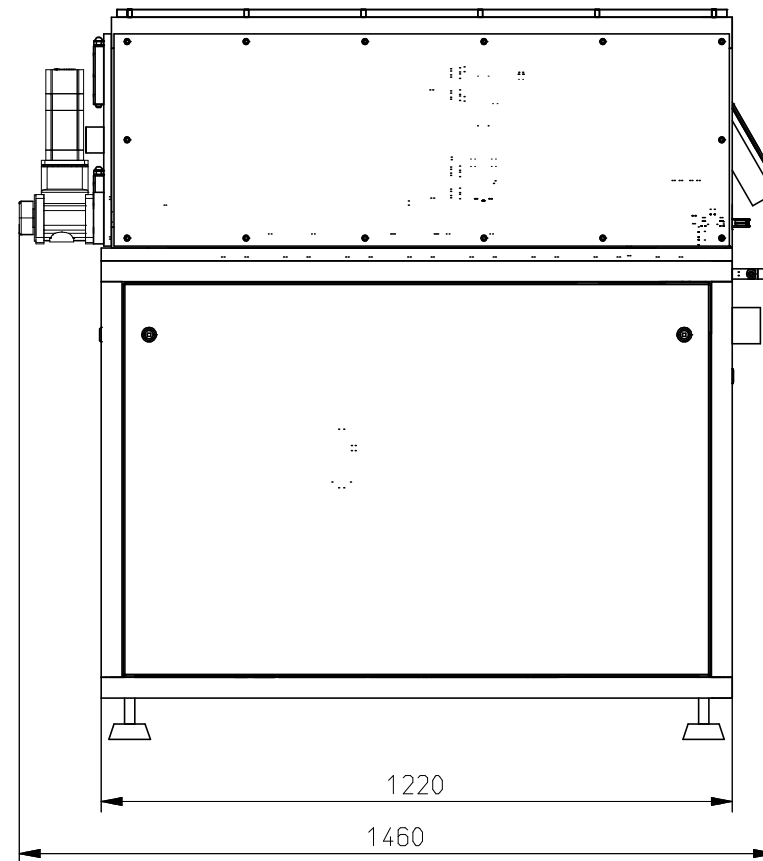
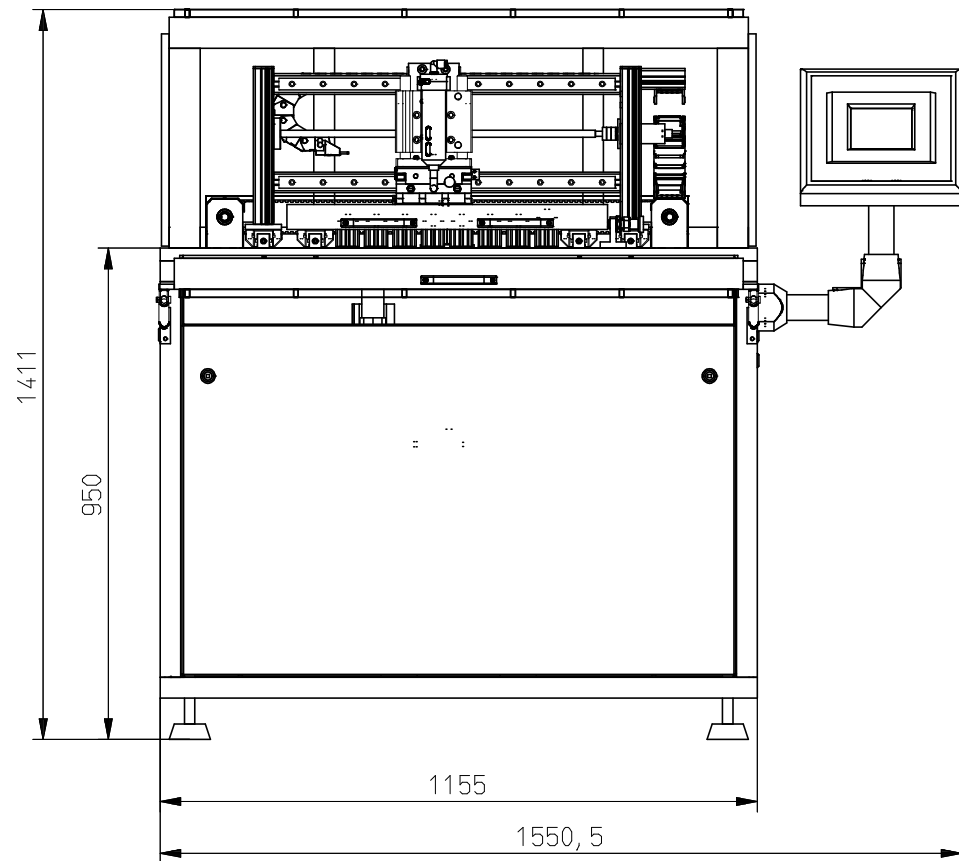
For more information, contact:

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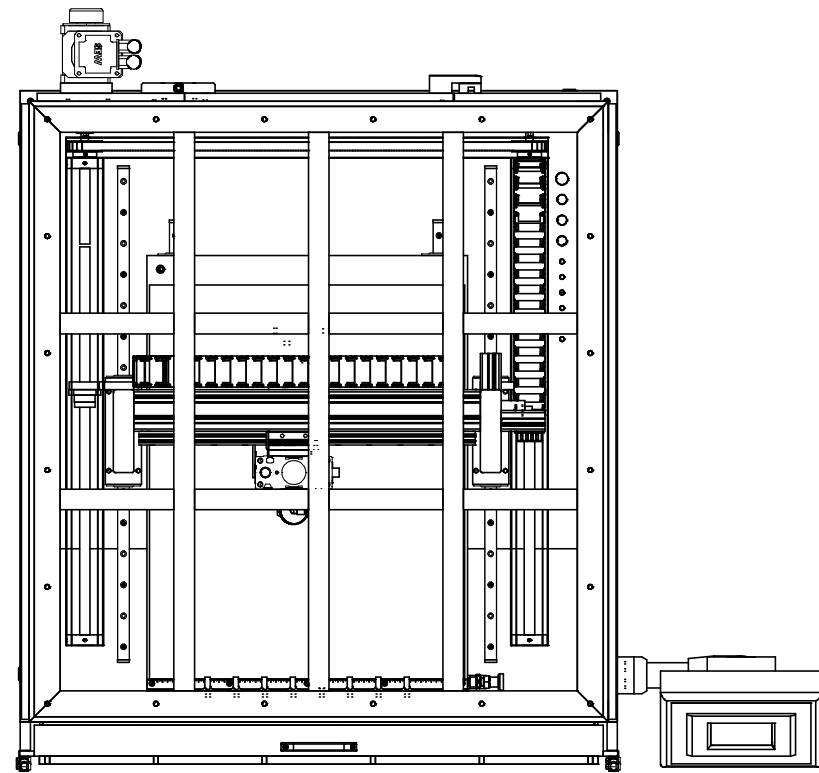
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Movement in
X – Y direction



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dimensions approx. 60x58x56 inch
 weight approx. 720 kg
 panel size max. 30x24 inch
 panel clamp holded
 central control Siemens S7
 Siemens Touch Panel
 Y-axis servo motor controlled
 X-axis step motor controlled
 electr. connection 3x480V PEN 60 HZ, 4 kW
 compressed air 88 psi
 free space around 20 inch
 room temperature 72°F +/- 3°F
 rel. humidity 50 +/- 10%

Technische Änderungen vorbehalten	MASS GmbH		Wilhelm-Lorenz-Str. 13-15 59590 Geseke Tel.: (02942) 9702-0 Fax.: (02942) 9702-30 eMail: info@mass-pcb.de		Maßstab 1:10	A2	Gewicht
			Datum Name		Maßblatt VHF 300 V		
			Bearb. 25.02.2009 Settemeyer				
			Gepr.				
			Norm				
		CAD: C:EBB34E05.S21		1561 00 000		0	Blatt
Zust.	Änderung	Datum	Name	Urspr.	Ers. f.:	Ers. d.:	Bl.